SUBMODULE SCREENING TEST PLAN
For Modules H1, H2 and H3

TEST	CONDITION	MIL-STD-750 TEST METHOD
Storage	T_A = +175°C for 24 hours	1032
Temp Cycle	-65°C to +175°C, 20 cycles, 15 minutes each extreme	1051
Acceleration	20KG, Y1 axis, no hold time	2006
Electrical	Reverse Current (I_R) @ rated V_{WM} Breakdown Voltage ($V_{(BR)}$) @ I_T	4016 4022
Pulse	20 pulses @ rated I_{PP}, t_p = 10 x 1000µs	
Electrical	Reverse Current (I_R) @ rated V_{WM}	4016
Burn-In	T_A = +125°C @ rated V_{WM} for 96 hours	1038
Electrical	Reverse Current (I_R) @ rated V_{WM}, D-I_R = 50% or 1µA, whichever is greater Breakdown Voltage ($V_{(BR)}$) @ I_T, D-$V_{(BR)}$ ±2% from initial reading	4016 4022
Fine Leak	5 x 10^{-8} atmcc/sec	1071G/H
Gross Leak	T_A = +125°C for 1 minute, no bubbles	1071C/D
Group A	Reverse Current (I_R) @ rated V_{WM} Breakdown Voltage ($V_{(BR)}$) @ I_T Clamping Voltage (V_C) @ I_{PP}, t_p = 10 x 1000µs Forward Voltage (V_F) @ I_F, t_p = 8.3ms	4016 4022 4011

Note: For bidirectional devices, test both polarities – split hours on Burn-in test and surge pulse to 50% each polarity.

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